Amendments to the Abstract:

Please amend the abstract as follows.

Presented is a [[A]] method for the production of a plurality of optoelectronic semiconductor chips each having a plurality of structural elements with respectively at least one semiconductor layer. The method involves providing a chip composite base that includes having a substrate and a growth surface. A mask material layer is formed on the growth surface[[,]]. The said mask material layer having includes a multiplicity of windows, most of which have having an average extent of less than or equal to 1 µm. In this case, a A mask material is chosen in such a way so that a semiconductor material of the semiconductor layer that is to be grown in a later method step essentially cannot grow on said the mask material or can grow in a substantially worse manner in comparison with the growth surface. Subsequently, semiconductor layers are deposited essentially simultaneously onto regions of the growth surface that lie within the windows. A further method step is singulation of the The chip composite base with applied material is singulated to form semiconductor chips. An optoelectronic semiconductor component is produced according to the method.